

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1 Claims 1-28 (cancelled):
2

3 Claim 29 (new): A method for using a guide for tip to transmission
4 path contact, said method comprising the steps of:

5 (a) providing at least one guide insulator having at least one
6 passageway defined by said at least one guide insulator,
7 said at least one passageway having a tip passageway end
8 and a transmission path passageway end, said tip
9 passageway end suitable for at least partially
10 accommodating said tip, said transmission path passageway
11 end suitable for at least partially accommodating a
12 transmission path, said at least one guide insulator having at
13 least one passageway that includes a contact enhancing
14 mechanism;

15 (b) interconnecting said guide insulator with a circuit board
16 component having at least one transmission path such that
17 said transmission path is at least partially accommodated
18 within said transmission path passageway, interconnecting
19 said contact enhancing mechanism with said at least one
20 transmission path; and

21 (c) probing said transmission path by inserting a tip of an
22 electronic test probe into said tip passageway end and
 touching said tip to said contact enhancing mechanism, such
 that said tip electrically contacts said transmission path.

23

1 Claim 30 (new): The method of claim 29, wherein step (c) is performed
2 after step (b).
3

1 Claim 31 (new): The method of claim 29, further comprising the step of
2 removing said tip of said electronic test probe while said guide insulator remains
3 interconnected with said circuit board component.
4

1 Claim 32 (new): The method of claim 29, said step of providing at least
2 one guide insulator further comprising the step of providing at least one guide insulator
3 that is removably interconnectable with a circuit board component having at least one
4 transmission path.
5

1 Claim 33 (new): The method of claim 29, wherein using said guide in
2 steps (b) and (c) facilitates relatively secure contact between said tip and said
3 transmission path.
4

1 Claim 34 (new): The method of claim 29, said tip passageway end
2 guiding said tip towards said transmission path.
3

1 Claim 35 (new): A method for using a guide for tip to transmission
2 path contact, said method comprising the steps of:

3 (a) providing at least one guide insulator having at least one
4 passageway defined by said at least one guide insulator,
5 said at least one passageway having a tip passageway end
6 and a transmission path passageway end, said tip
7 passageway end suitable for at least partially
8 accommodating said tip, said transmission path passageway

9 end suitable for at least partially accommodating a
10 transmission path;

11 (b) interconnecting said guide insulator with a circuit board
12 component having at least one transmission path such that
13 said transmission path is at least partially accommodated
14 within said transmission path passageway; and

15 (c) probing said transmission path by inserting a tip of an
16 electronic test probe into said tip passageway end such that
17 said tip electrically contacts said transmission path;

18 (d) wherein step (c) is performed after step (b).
19

1 Claim 36 (new): The method of claim 35, said step of providing at least
2 one guide insulator further comprising the step of providing at least one guide insulator
3 having at least one passageway that includes a contact enhancing mechanism.
4

1 Claim 37 (new): The method of claim 35, further comprising the step of
2 removing said tip of said electronic test probe while said guide insulator remains
3 interconnected with said circuit board component.
4

1 Claim 38 (new): The method of claim 35, said step of providing at least
2 one guide insulator further comprising the step of providing at least one guide insulator
3 that is removably interconnectable with a circuit board component having at least one
4 transmission path.
5

1 Claim 39 (new): The method of claim 35, wherein using said guide in
2 steps (b) and (c) facilitates relatively secure contact between said tip and said
3 transmission path.
4

1 Claim 40 (new): The method of claim 35, said tip passageway end
2 guiding said tip towards said transmission path.
3

1 Claim 41 (new): A method for using a guide for tip to transmission
2 path contact, said method comprising the steps of:

- 3 (a) providing at least one guide insulator having at least one
4 passageway defined by said at least one guide insulator,
5 said at least one passageway having a tip passageway end
6 and a transmission path passageway end, said tip
7 passageway end suitable for at least partially
8 accommodating said tip, said transmission path passageway
9 end suitable for at least partially accommodating a
10 transmission path;
11 (b) interconnecting said guide insulator with a circuit board
12 component having at least one transmission path such that
13 said transmission path is at least partially accommodated
14 within said transmission path passageway; and
15 (c) probing said transmission path by inserting a tip of an
16 electronic test probe into said tip passageway end such that
17 said tip electrically contacts said transmission path.
18

1 Claim 42 (new): The method of claim 41, said step of providing at least
2 one guide insulator further comprising the step of providing at least one guide insulator
3 having at least one passageway that includes a contact enhancing mechanism.
4

1 Claim 43 (new): The method of claim 42, said step of providing at least
2 one guide insulator having at least one passageway that includes a contact enhancing
3 mechanism further comprising the step of providing at least one guide insulator having
4 at least one passageway having a contact enhancing mechanism selected from a group
5 consisting of:

- 6 (a) solid contact enhancing mechanism;
- 7 (b) combination contact enhancing mechanism; and
- 8 (c) soft contact enhancing mechanism.

9
1 Claim 44 (new): The method of claim 41, further comprising the step of
2 removing said tip of said electronic test probe while said guide insulator remains
3 interconnected with said circuit board component.

4
1 Claim 45 (new): The method of claim 41, said step of providing at least
2 one guide insulator further comprising the step of providing at least one guide insulator
3 that is removably interconnectable with a circuit board component having at least one
4 transmission path.

5
1 Claim 46 (new): The method of claim 41, wherein said transmission path
2 is at least partially accommodated within said transmission path passageway before
3 said tip of an electronic test probe is inserted into said tip passageway end.

4
1 Claim 47 (new): The method of claim 41, wherein using said guide in
2 steps (b) and (c) facilitates relatively secure contact between said tip and said
3 transmission path.

4
1 Claim 48 (new): The method of claim 41, said tip passageway end
2 guiding said tip towards said transmission path.

1 Claim 49 (new): The method of claim 41, wherein said step of providing at
2 least one guide insulator further comprises the step of providing at least one guide
3 insulator having a tip passageway end with at least one guide enhancing mechanism
4 selected from the group consisting of:

- 5 (a) a funnel shaped opening; and
6 (b) an enlarged, partial funnel shaped opening.
7

1 Claim 50 (new): The method of claim 41, wherein said step of providing at
2 least one guide insulator having at least one passageway further comprises the step of
3 providing at least one guide insulator having fewer passageways than the number of
4 transmission paths of the device to be probed.
5

1 Claim 51 (new): The method of claim 41, wherein said step of providing at
2 least one guide insulator having at least one passageway further comprises the step of
3 providing at least one guide insulator having two passageways.
4

1 Claim 52 (new): The method of claim 41, wherein said step of providing at
2 least one guide insulator further comprises the step of providing at least one guide
3 insulator having at least one mounting apparatus and at least one divider guide
4 insulator, each divider guide insulator positionable between close transmission paths.
5

1 Claim 53 (new): The method of claim 41, wherein said step of providing at
2 least one guide insulator further comprises the step of providing at least two guide
3 insulators, said at least two guide insulators being adjustable in relation to each other.
4